

Development of a High-Speed High-Performance Microfabricated Gas Chromatograph

SAND2007-0927C

Pittcon 2007 – Chicago, IL

Joshua Whiting
Sandia National Laboratories

Sandia National Laboratories

Robert J. Simonson

Al Staton, Steve Howell, Shawn Dirk, Ron Manginell,
Alex Robinson, John Anderson, Paul Galambos,
Kamyar Rahimian, Randy Shul, Davor Copic, Darin
Graf

Louisiana State University

Ed Overton

Jost Goettert, Abhinav Bhushan
Dawit Yemane, H.P. Dharmasena

California Institute of Technology

Michael Roukes

Ed Meyers, Mo Li, J. Sequoyah Aldridge, Hong Tang*

*now at Yale

Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company,
for the United States Department of Energy under contract DE-AC04-94AL85000.

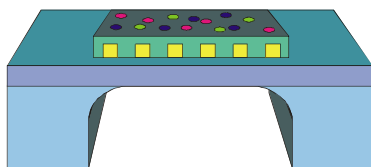
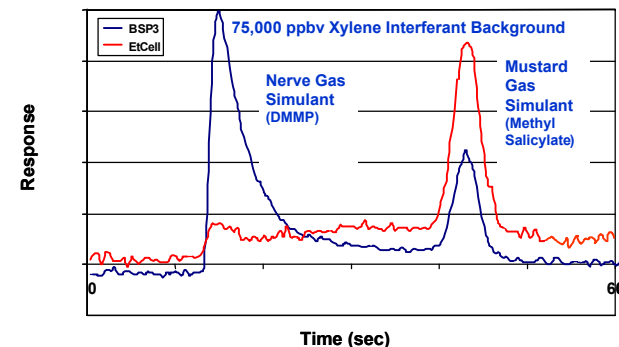
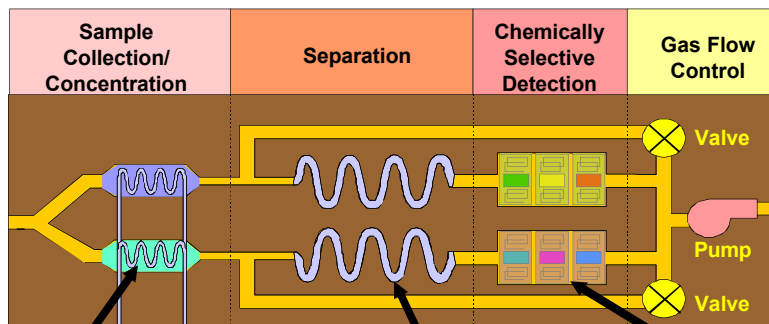


μ ChemLab™ at Sandia National Laboratories

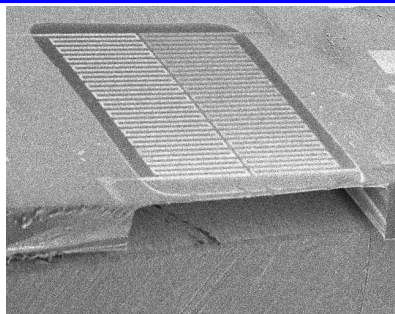
Hand-held chemical analysis system that uses three microfabricated stages.



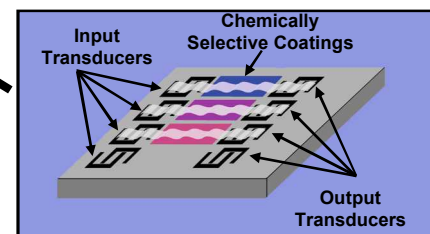
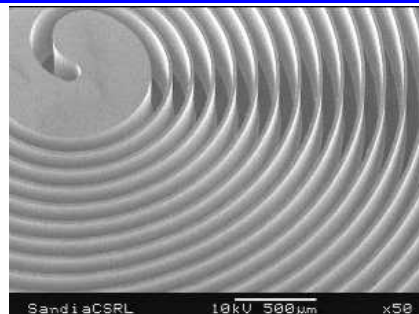
- 8"x4"x2"
- 2 min. analysis
- 4W max. power



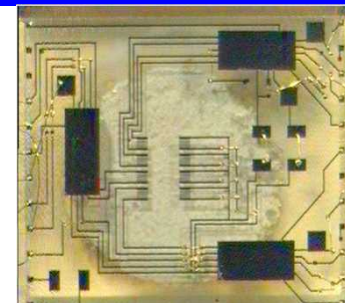
Preconcentrator accumulates species of interest



Gas Chromatograph separates species in time



Acoustic Sensors provide sensitive detection



Over a decade of development in small, low power, selective gas chromatographs.



Next Generation Development

Program Goals:

High Speed, High Performance GC

- Size
 - Small Size
 - **<20cm³ Total Volume**
 - MEMS Integrated Components
- Speed
 - High Speed Separations
 - **8 components separated from 8 interferences in 4s**
 - Hydrogen Carrier Gas
- Power
 - Low Power
 - **<3J/analysis**
 - Catalytic Combustion of hydrogen for heating column
- Resolution
 - High Performance
 - **Total Analytical Peak Capacity >100 in 4s**
 - High Aspect Ratio MEMS (HARM) columns



Modeling Predicts *System* Efficiency Using Rectangular GC Columns

1st 3 terms model column performance, 4th term connects column to system

$$H = \underbrace{\frac{2D_g f_1 f_2}{\bar{u}}}_{\text{Longitudinal diffusion}} + \underbrace{\frac{(1 + 9k + 25.5k^2)}{105(k+1)^2} \frac{w^2}{D_g} \frac{f_1}{f_2} \bar{u}}_{\text{Mass Transport in the Mobile Phase}} + \underbrace{\frac{2}{3} \frac{k}{(k+1)^2} \frac{(w+h)^2 d_f^2}{D_s h^2} \bar{u}}_{\text{Mass Transport in the Stationary Phase}} + \underbrace{\frac{\Delta t^2 u^2}{L(k+1)^2}}_{\text{Extra-Column Band Broadening}}$$

\bar{u} – average linear carrier gas velocity

D_g – binary diffusion coefficient in gas phase

f_1 –Giddings-Golay gas compression correction factor

f_2 – Martin-James gas compression correction factor

k – retention factor

w – channel width

h – channel height

d_f – stationary phase film thickness

D_s – binary diffusion coefficient in stationary phase

L – column length

Δt – time correlating to extra column band broadening

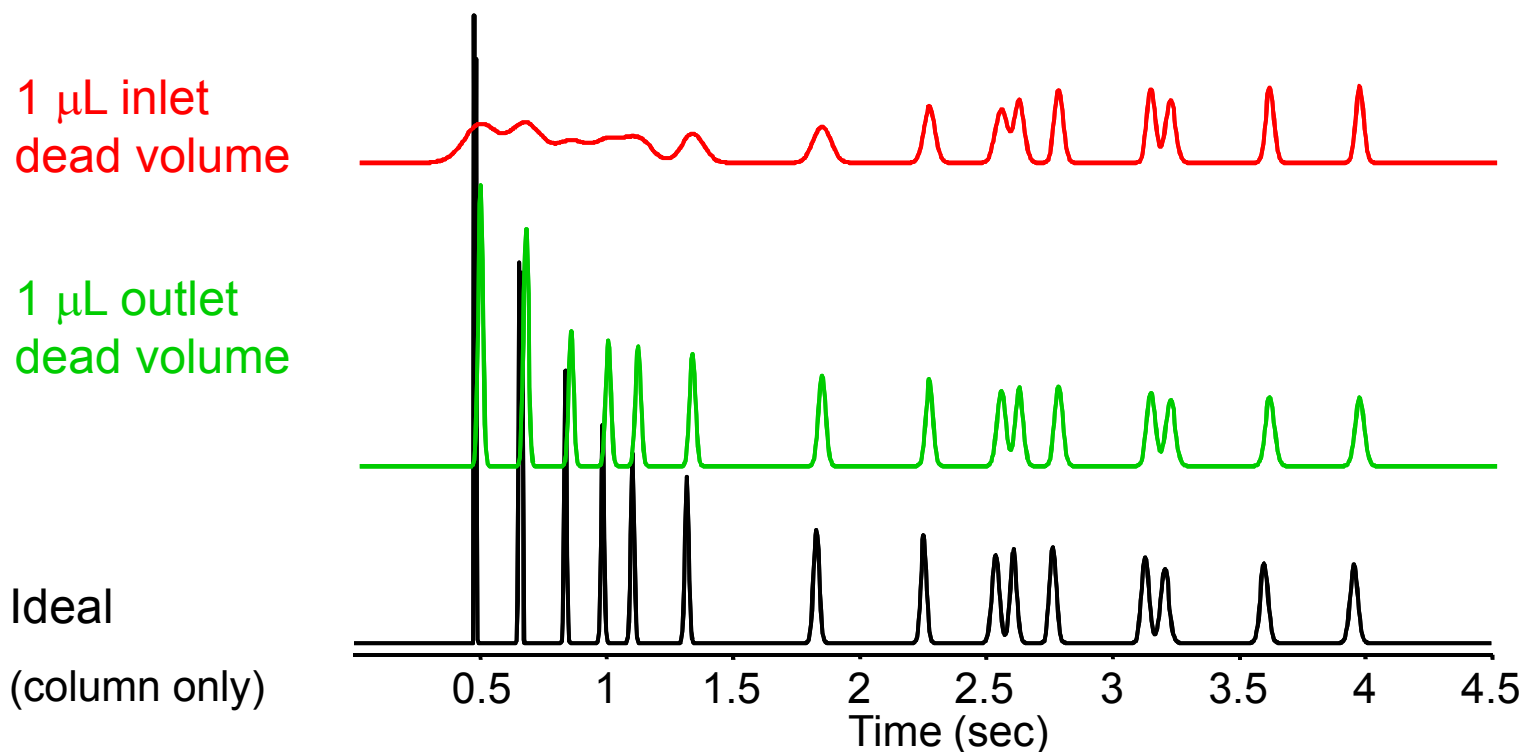
$$\Delta t = \frac{\text{inlet (or outlet) volume, cm}^3}{\text{gas flow rate, cm}^3/\text{sec}}$$



Integration Driver: Modeled GC Band Broadening

Ahn and Brandani Model – Dec. 2005

T-programmed 8/8 separation

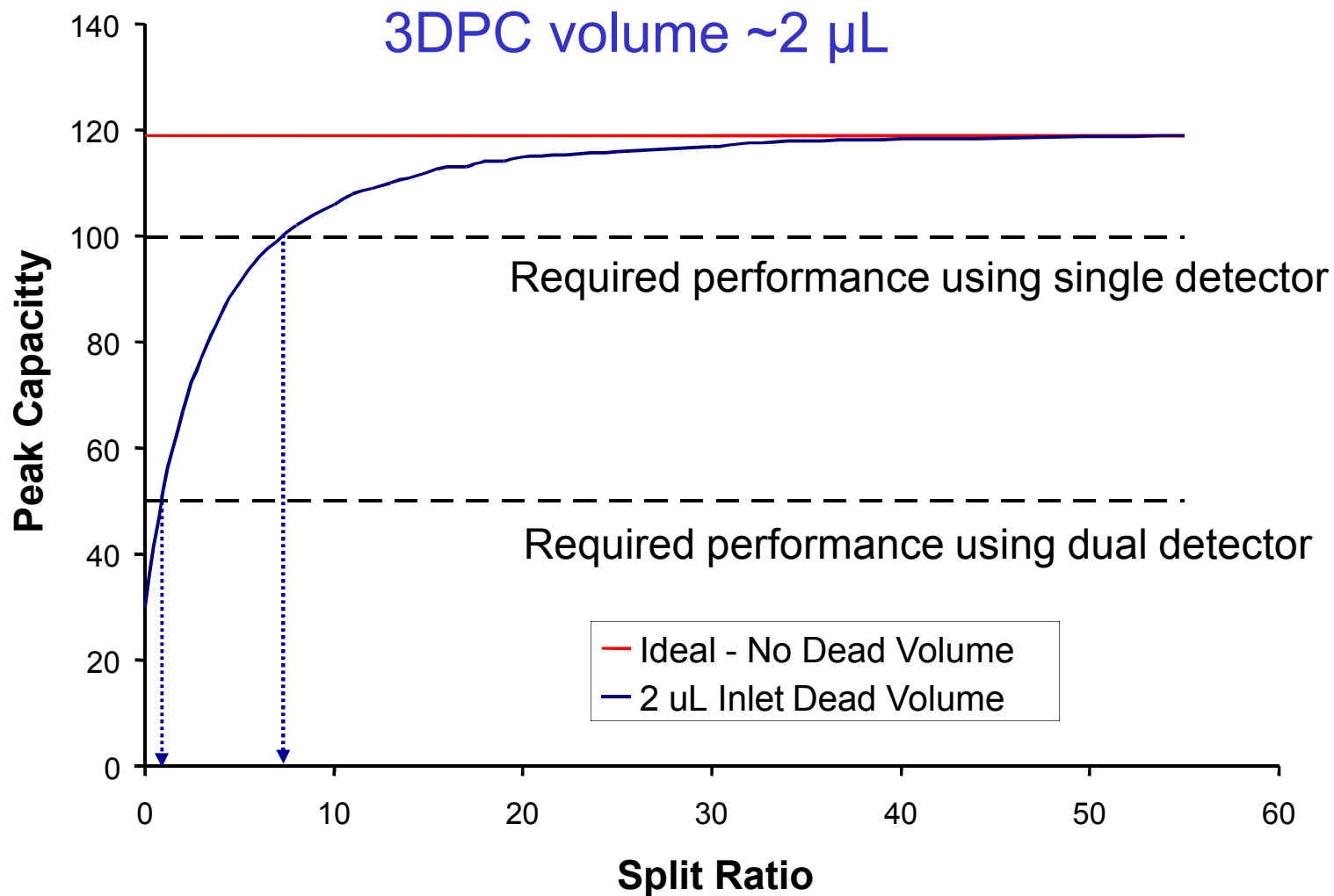


Inlet dead volume costs more than outlet dead volume due to carrier gas compressibility: $(\text{cm}^3/\text{sec})_{\text{outlet}} > (\text{cm}^3/\text{sec})_{\text{inlet}}$

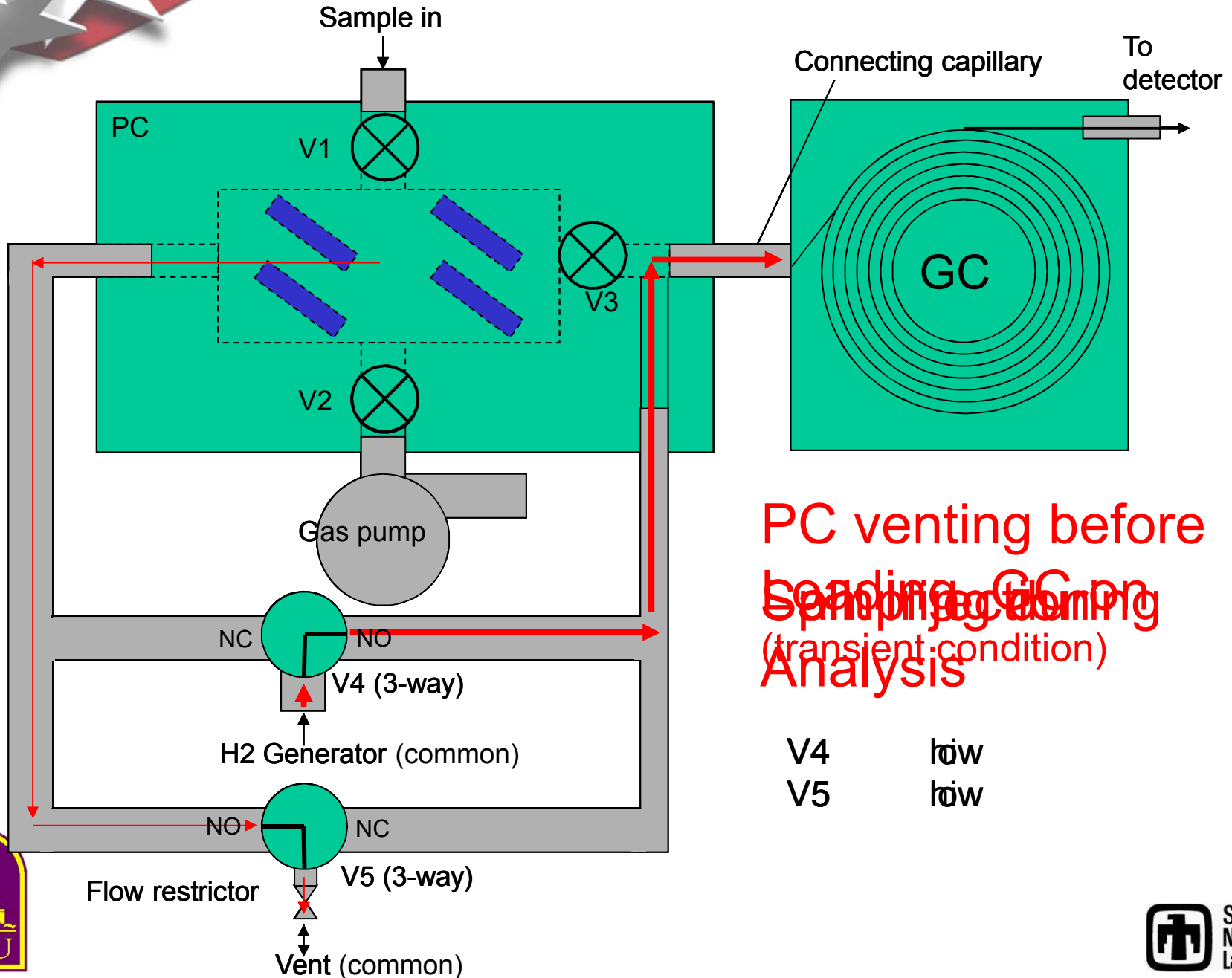


Mitigating the Effects of Inlet Dead Volume

GC Peak Capacity vs. Injection Split Ratio

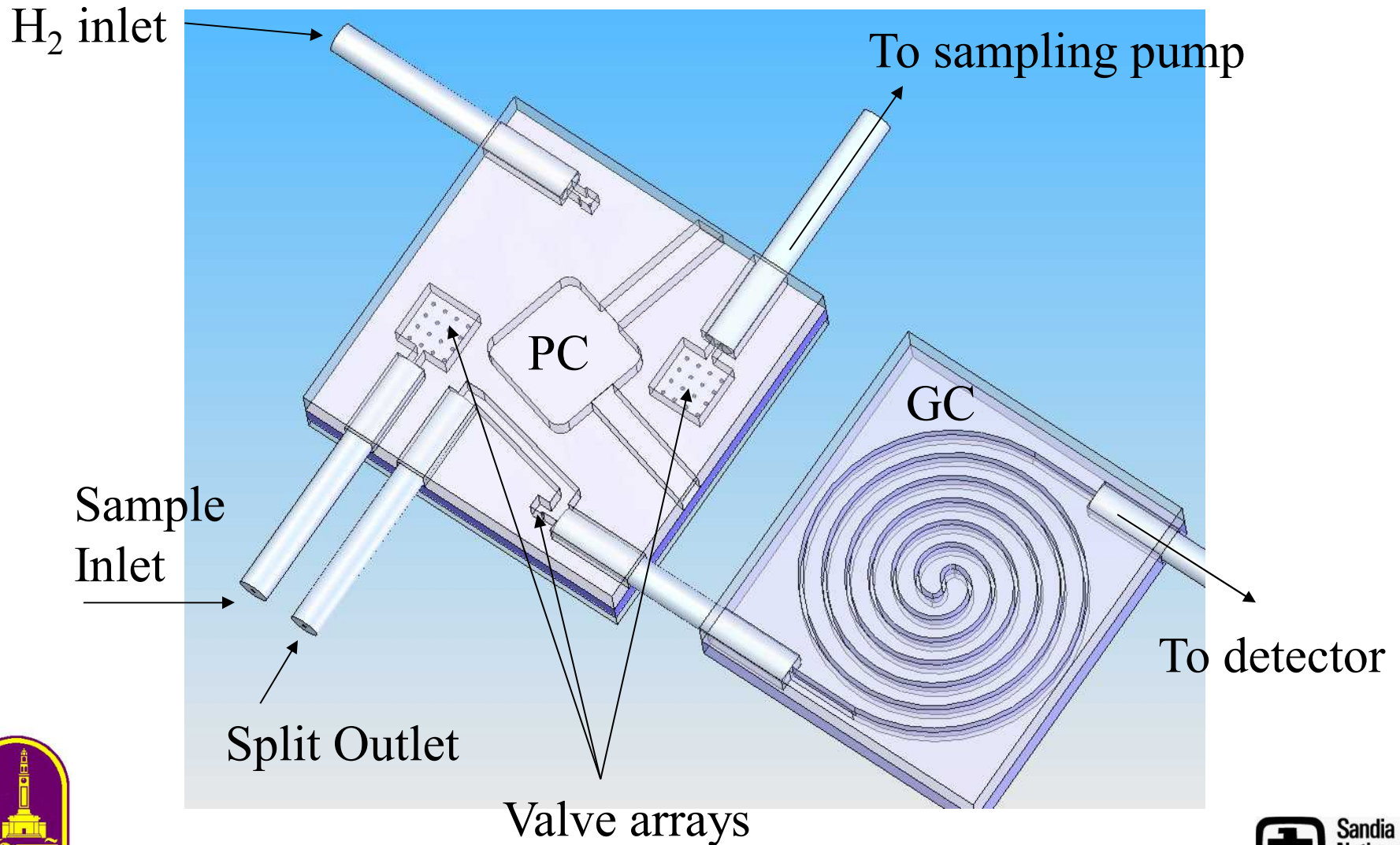


2 External Valve System Schematic

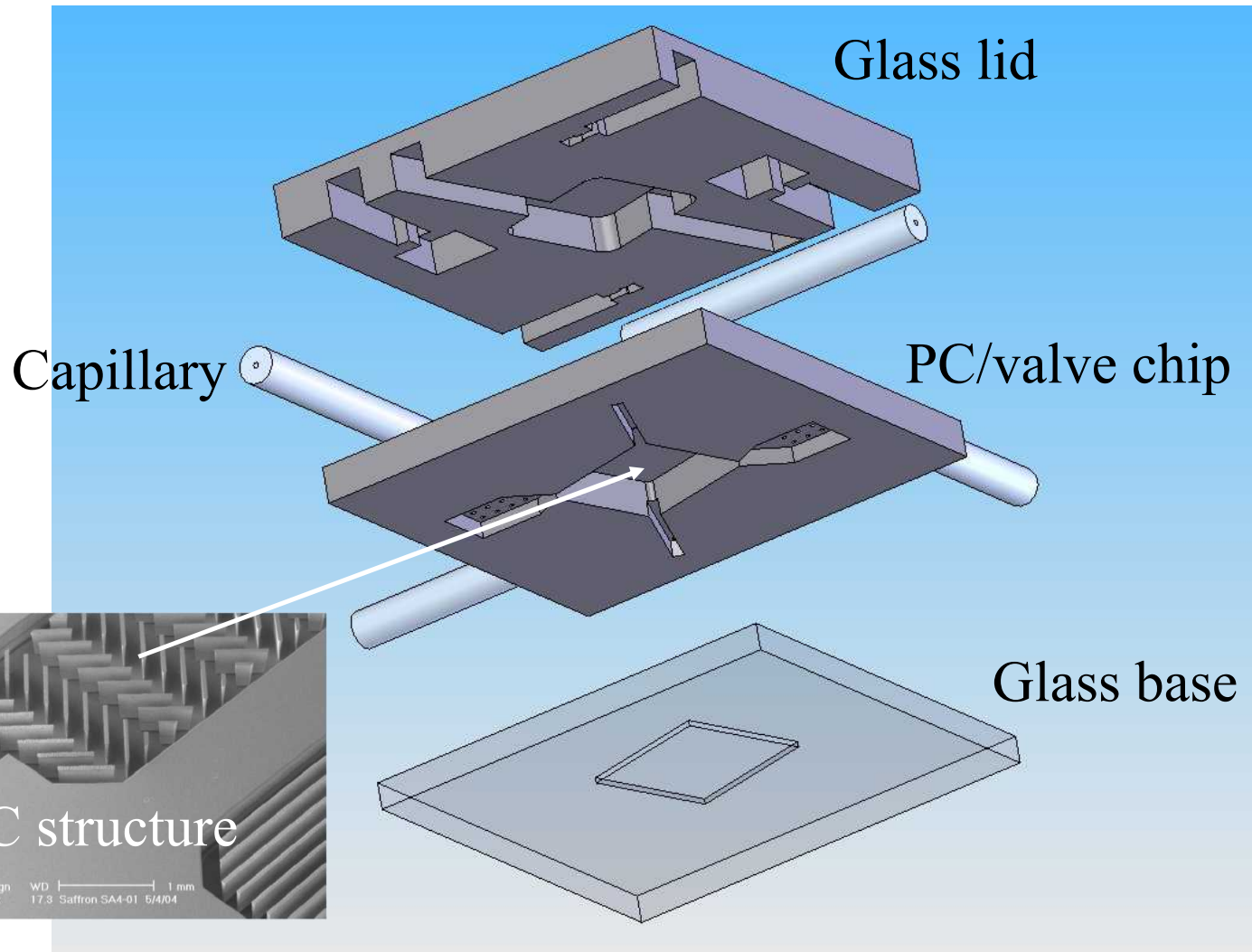


Hybrid Integration

MEMS valves on PC chip limit inlet volume

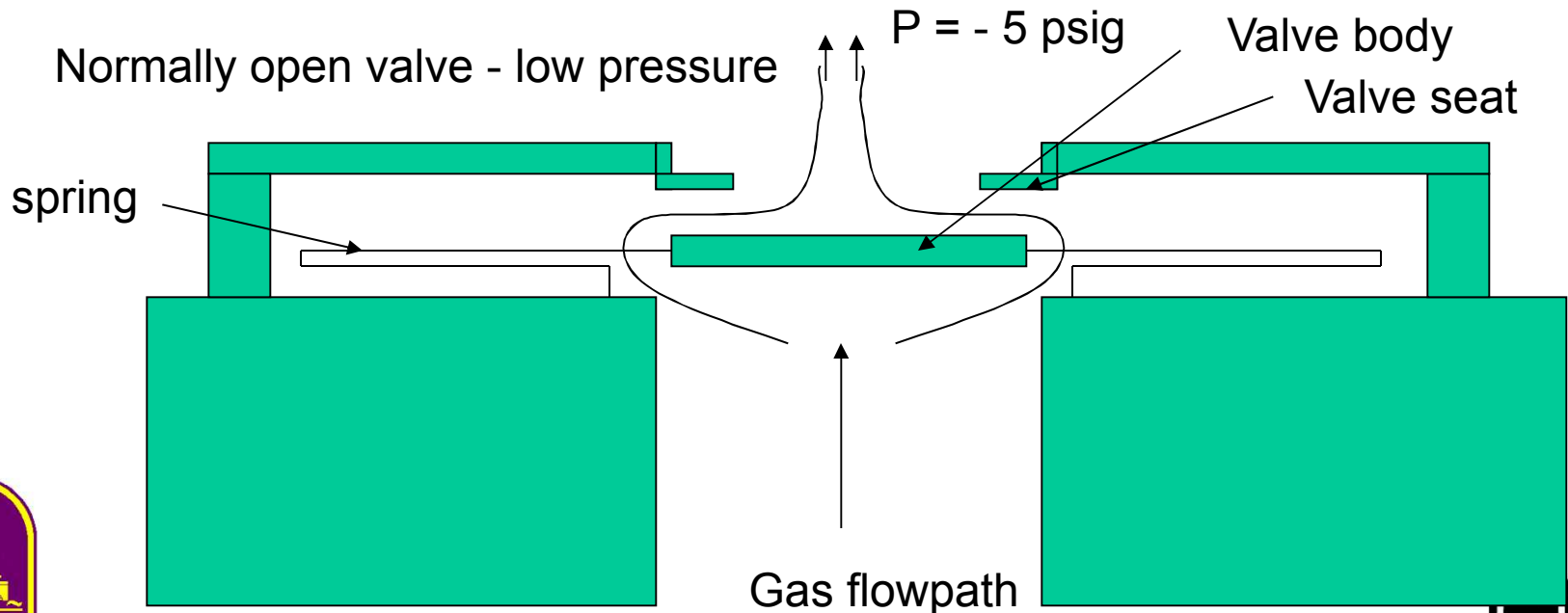


Exploded view from the bottom



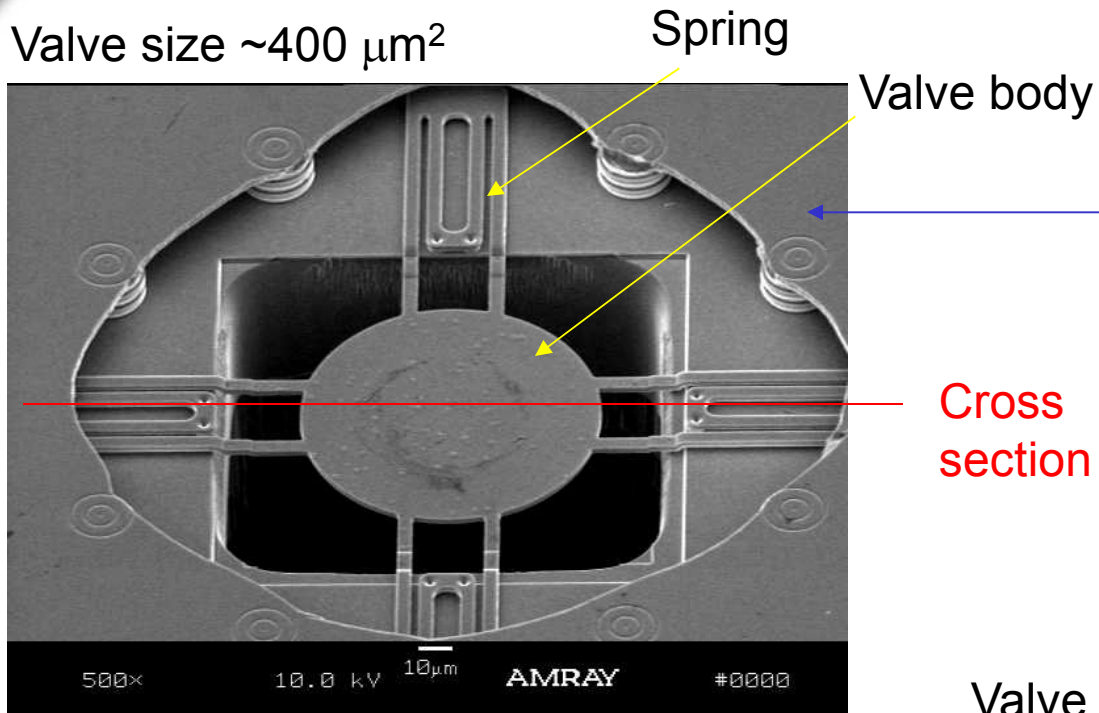
Passive Offset Check Valve design concept (normally open valve)

- Open one-way at low pressures
- Closed *in the same flow direction* at higher pressures
- A check valve with an offset.
- Our design uses a soft spring with properly selected stiffness, matched to:
 - Pressure requirement
 - Flow requirement
 - Orifice size



Valve 2 - SUMMiT™ design and fabrication

Valve size $\sim 400 \mu\text{m}^2$



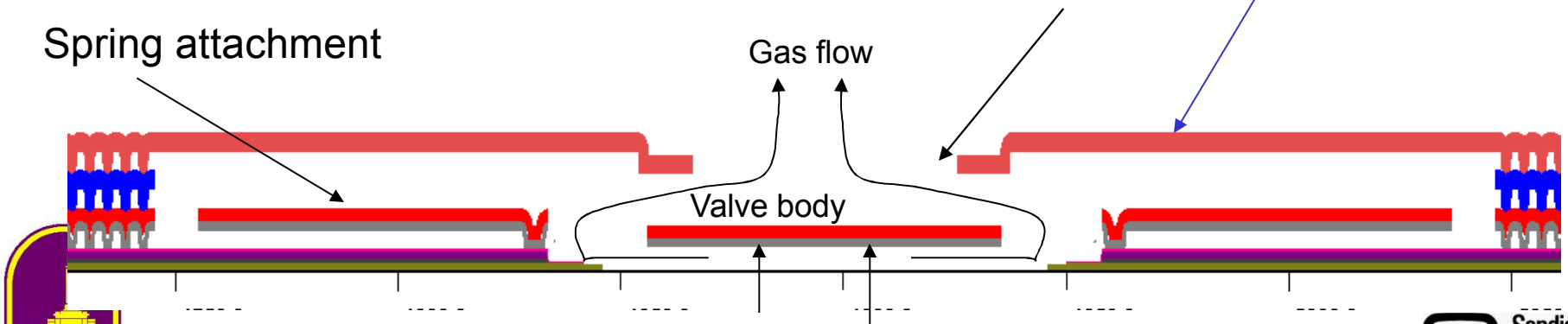
Upper poly-Si layer, which defines the valve orifice, is cut away in the micrograph

Spring attachment

Gas flow

Valve orifice

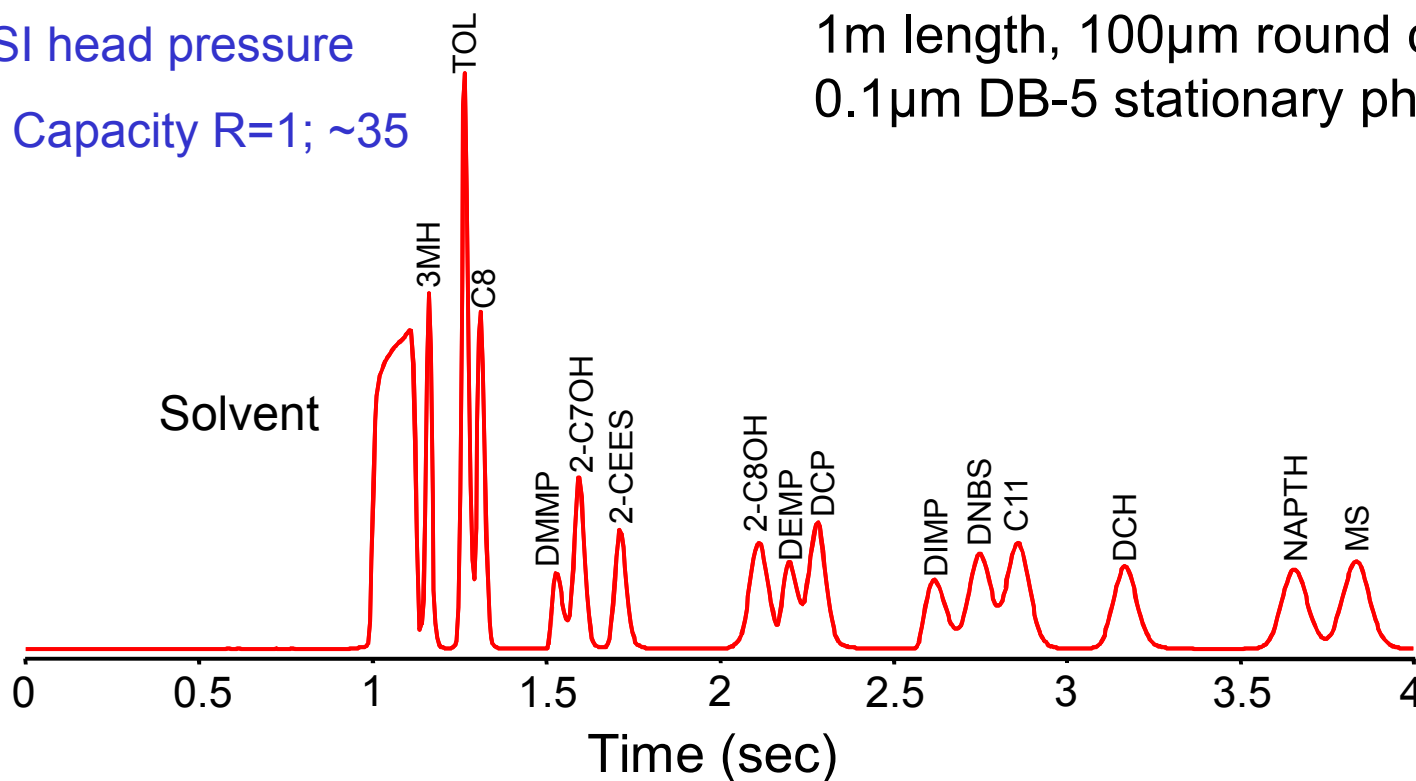
Valve body



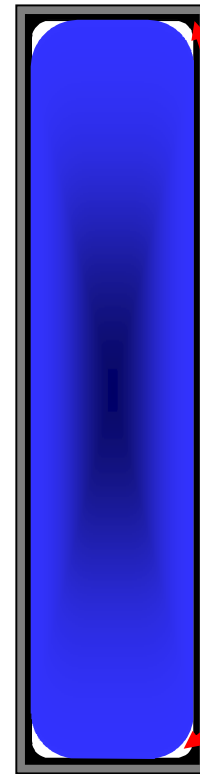
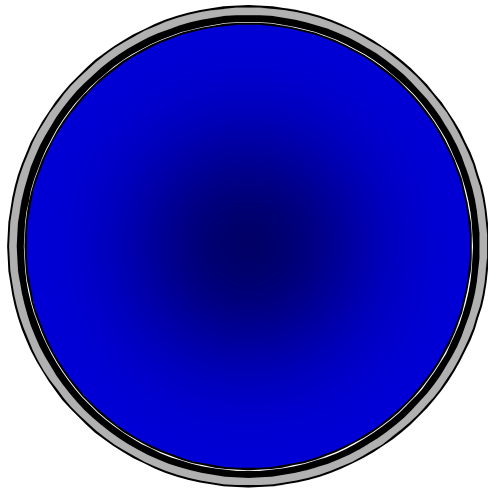
Separation of 16 Compounds in < 4 sec

- Temperature Programmed from 59 to 87 °C
- 30 PSI head pressure
- Peak Capacity $R=1$; ~35

8 CWA simulants
8 interferents
1m length, 100 μ m round column
0.1 μ m DB-5 stationary phase

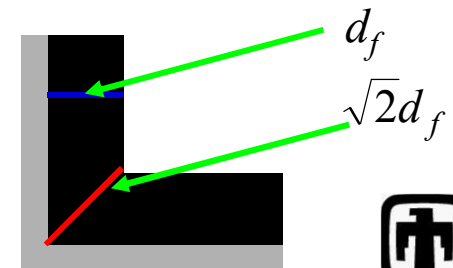
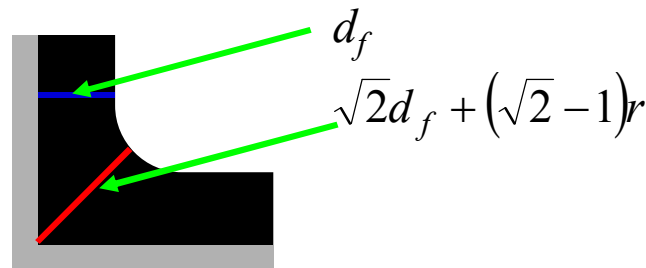
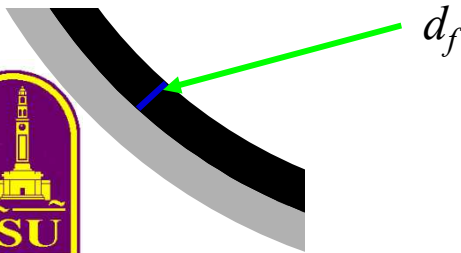


Round vs. HARM columns



- Flow restriction controlled by height
- Performance limited by width
- End effects
 - Film deposition often results in thicker phases in the corner
 - Dead spaces in corners

- Flow restriction and performance limited by radius
- Film deposition is uniform



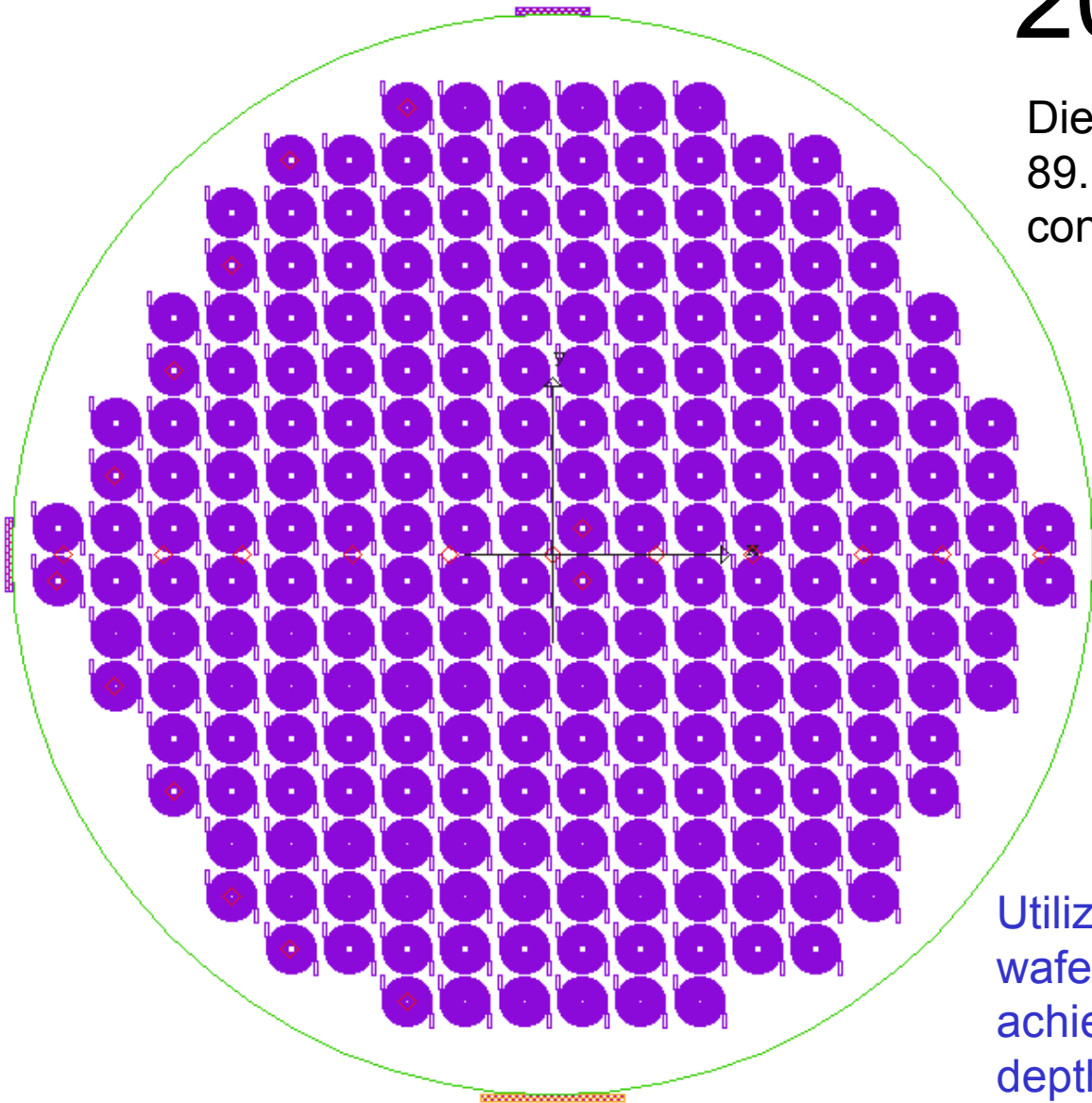
2090 GC

Die 1: 20 μm wide, 20 μm wall,
89.16 μm length between edge
connections; 98 occurrences

Die 3: 20 μm wide, 30 μm
wall, 73.58 μm length; 68
occurrences

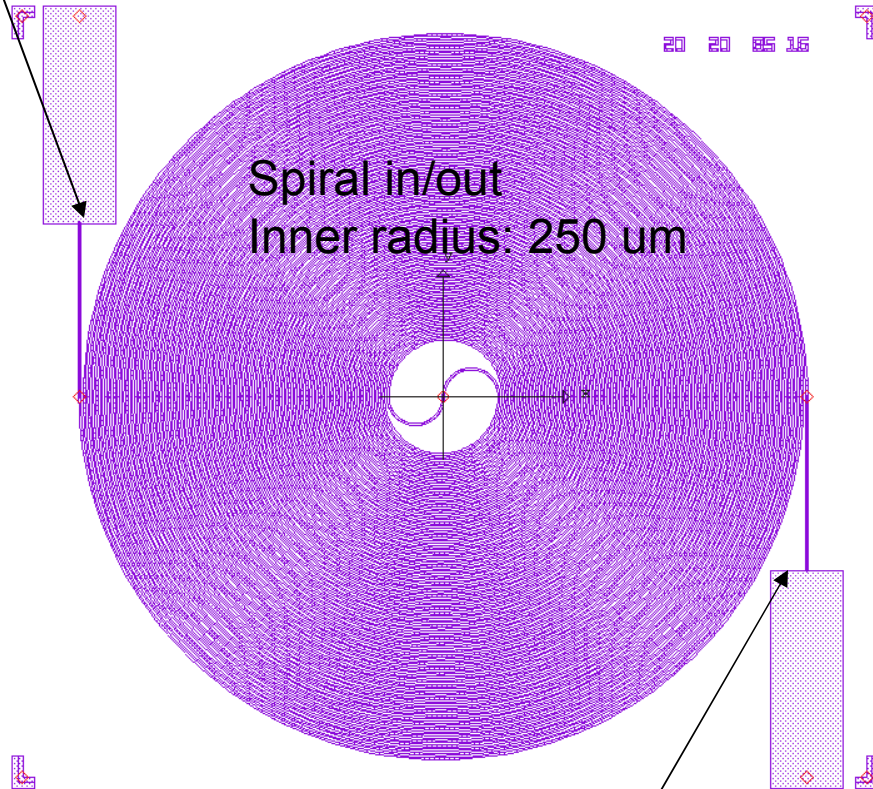
Die 2: Like Die 1 with
slight taper before edge
connections; 94
occurrences

Utilize BOX layer of SOI
wafer as etch stop to
achieve required column
depths



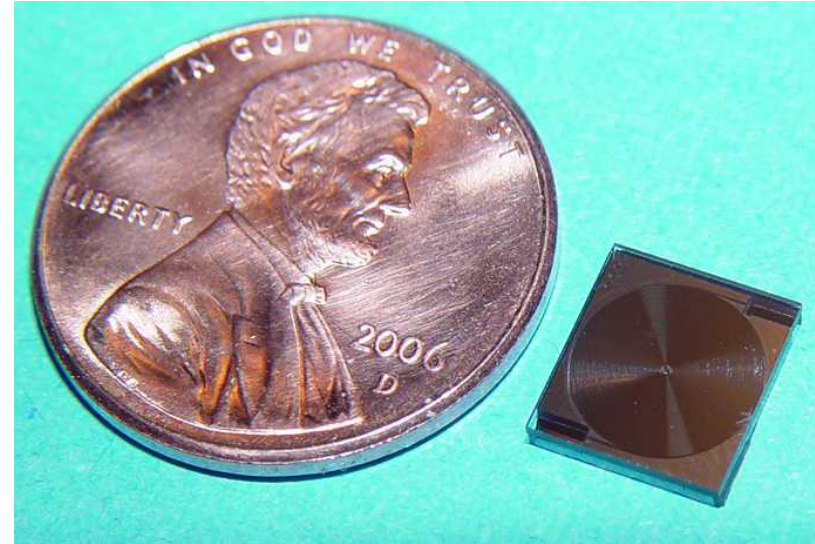
Sample Closeup: Die 1 fabricated on 20 um SOI (1 um BOX, 650 um Si)

Stated lengths
are measured
between here...



Spiral in/out
Inner radius: 250 um

...and here



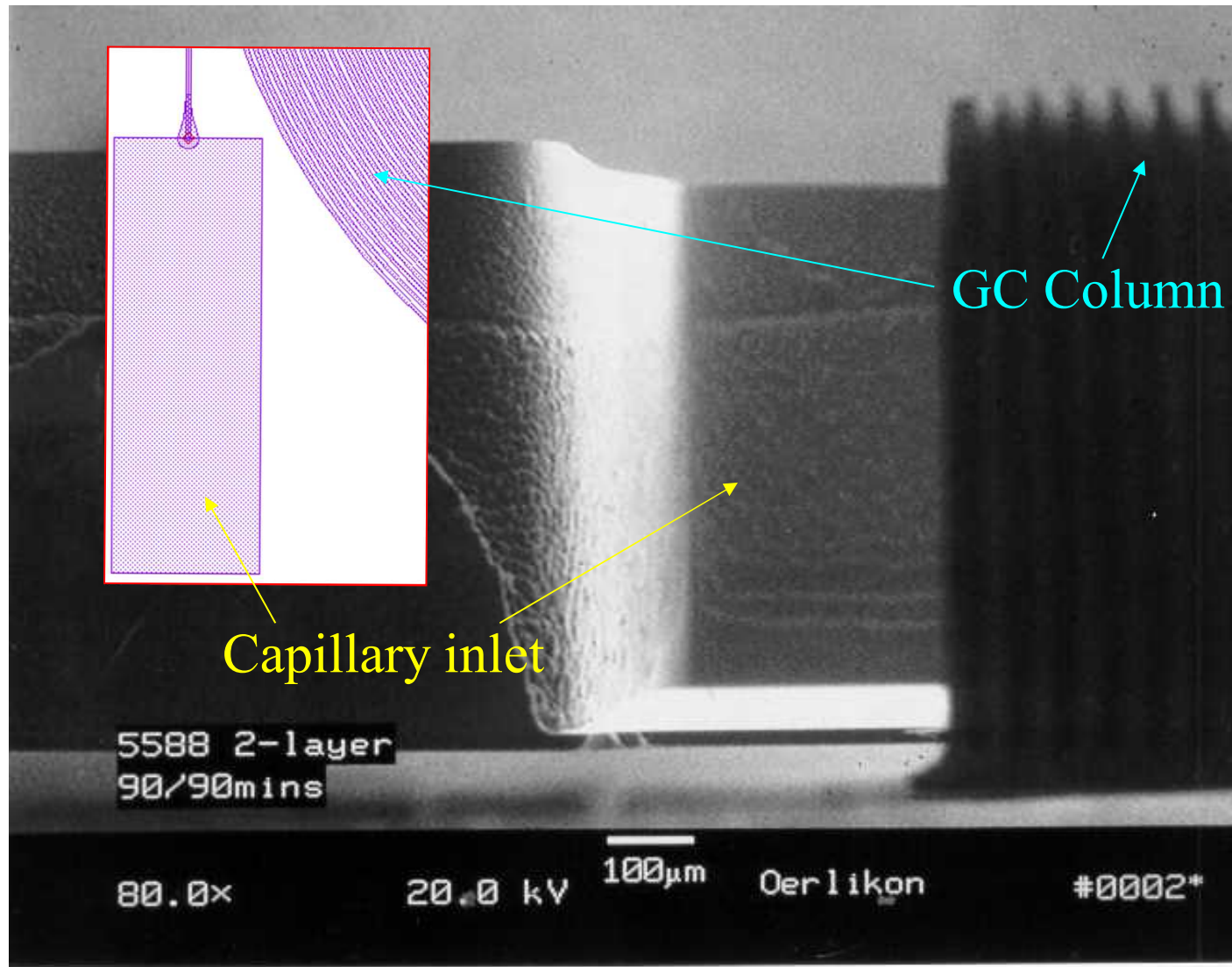
Die2 has a
slight taper

$$C_{tot} = 0.097 \frac{J}{K}$$



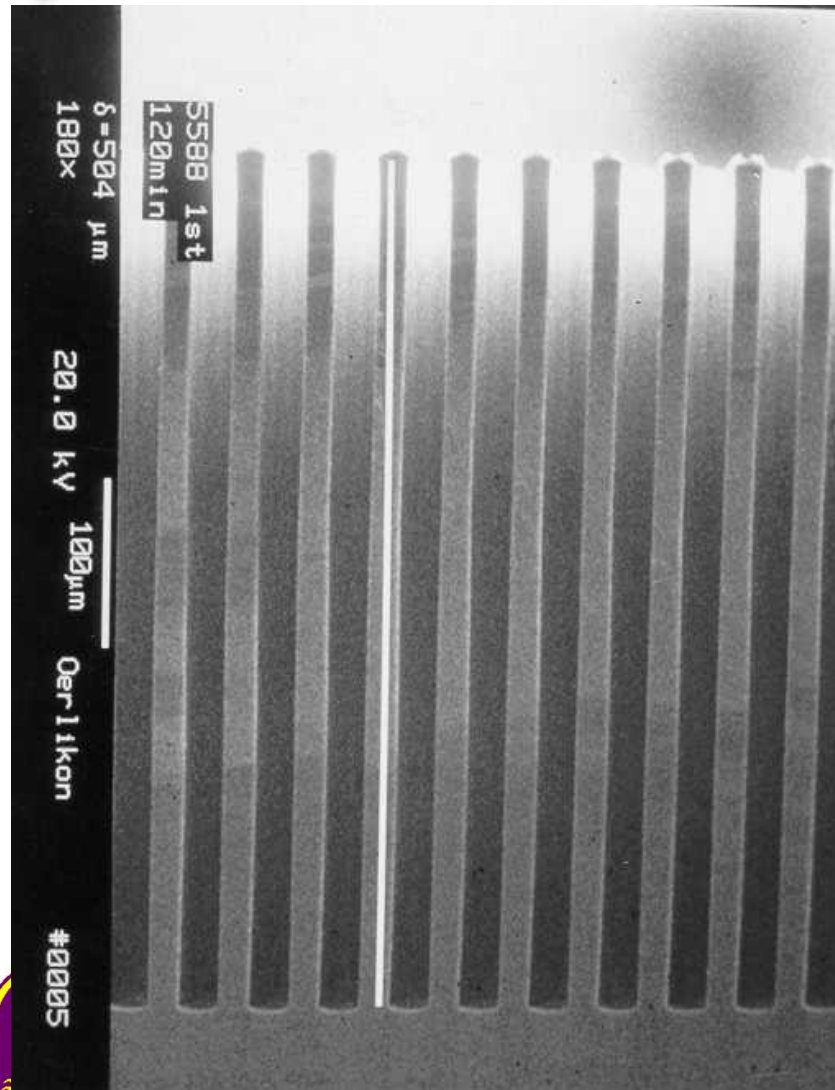
Delay layer has arrived and is awaiting processing

2090 GC test wafer - SEM

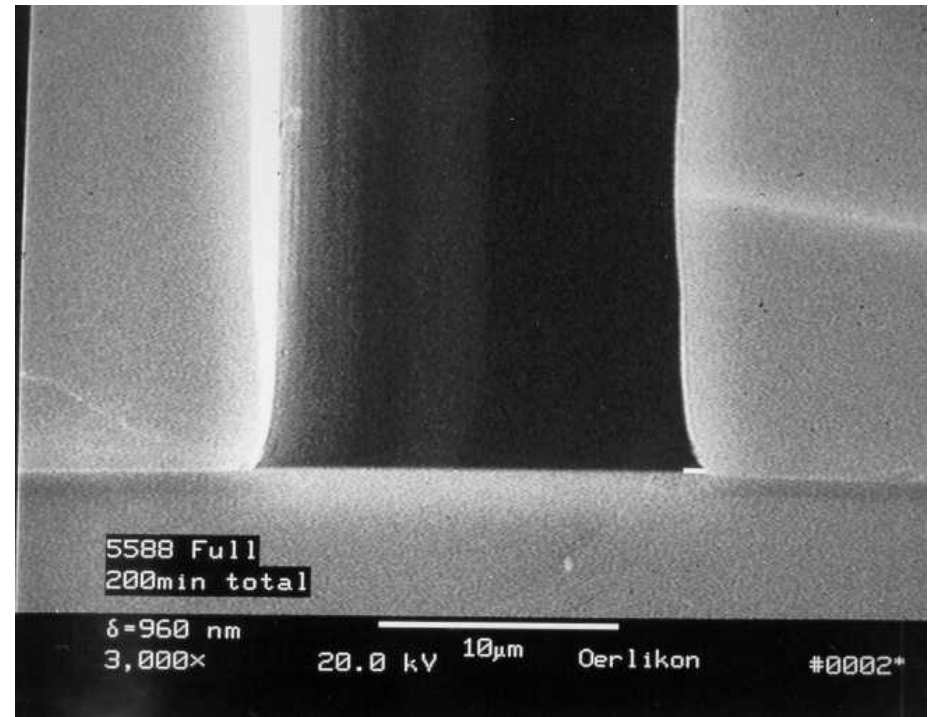


2090 GC test wafer - SEM

Column walls (first etch)



Bottom of column (2nd etch)

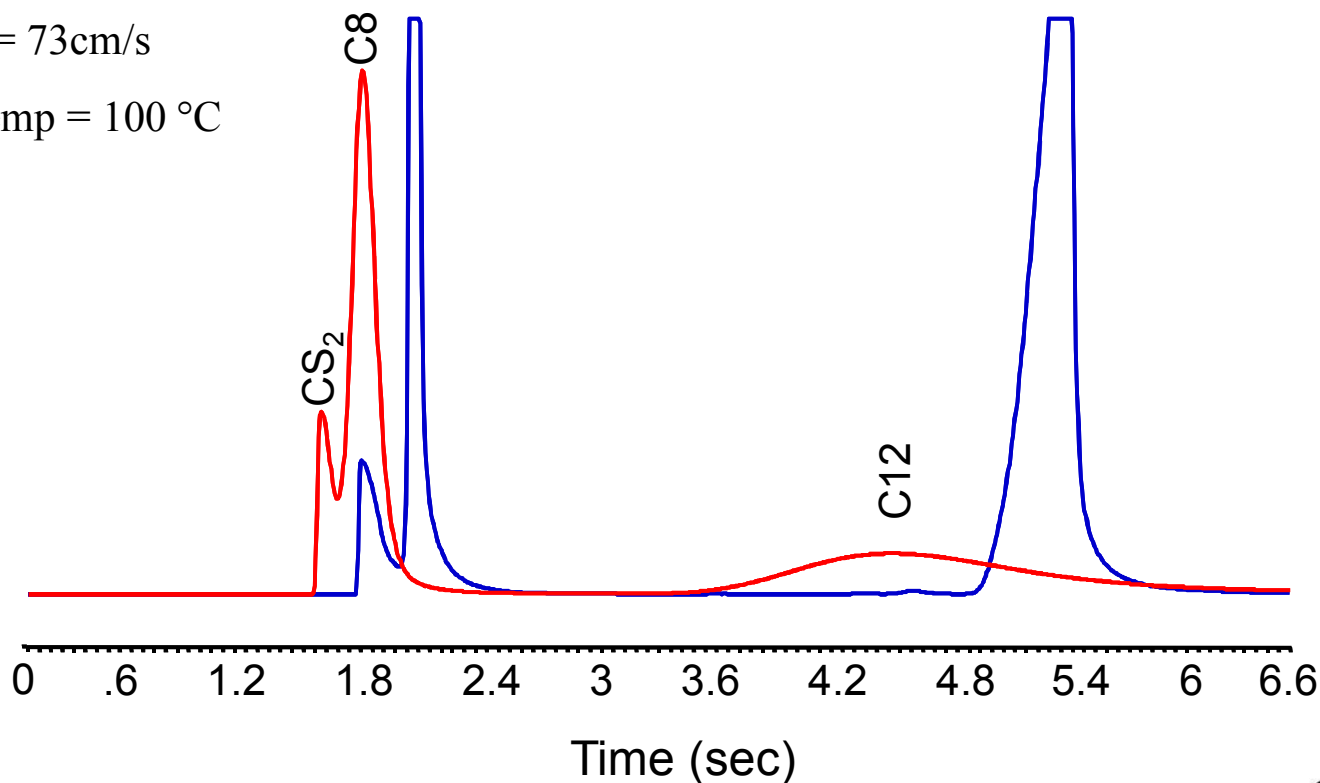


Coated Microcolumn Performance

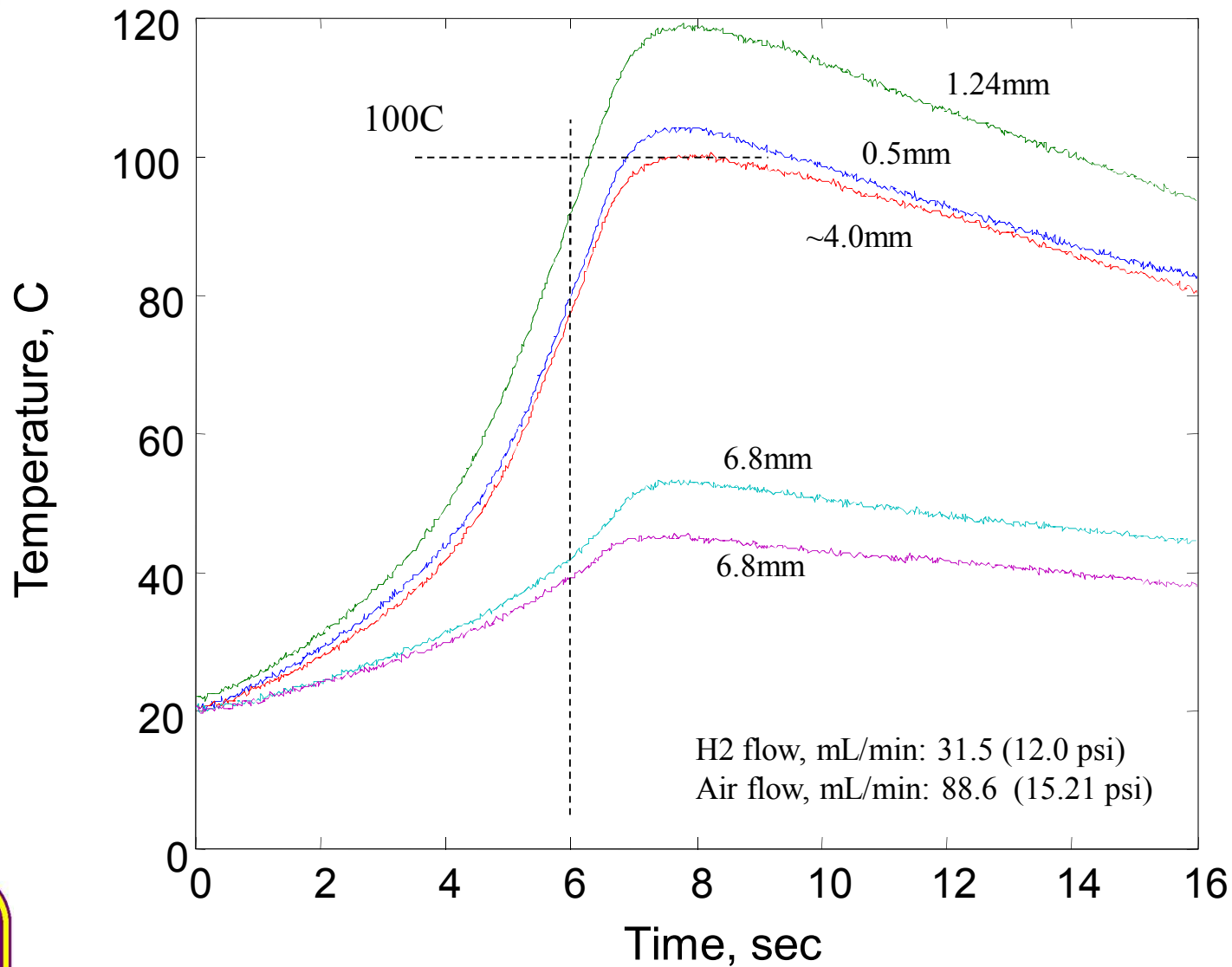
- 1 m length of 0.1 μ m RTX-1 100 μ m
- 20 μ m x 400 μ m 90cm coated with ~30nm PDMS

$\bar{u} = 73\text{cm/s}$

Temp = 100 °C



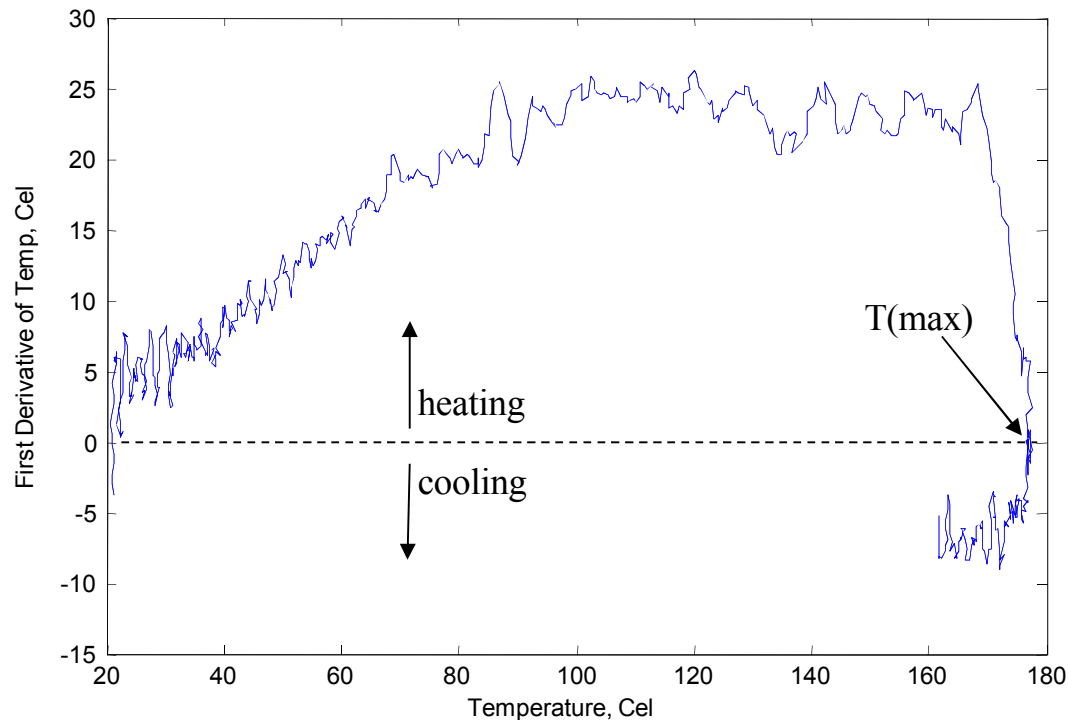
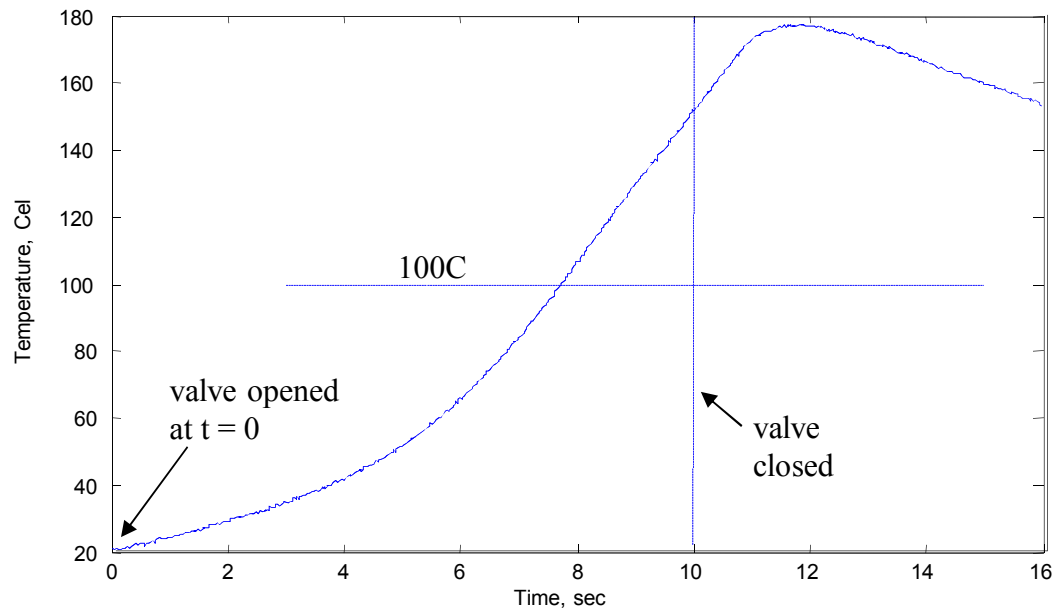
Example data, 2090 GC autocatalytic heating



Catalytic GC Heating

- Fuel autoignites
- Thermocouple T lags fuel valve switching
- Efficiency ~25%, can be improved with “burner” design

dT/dt vs.
T

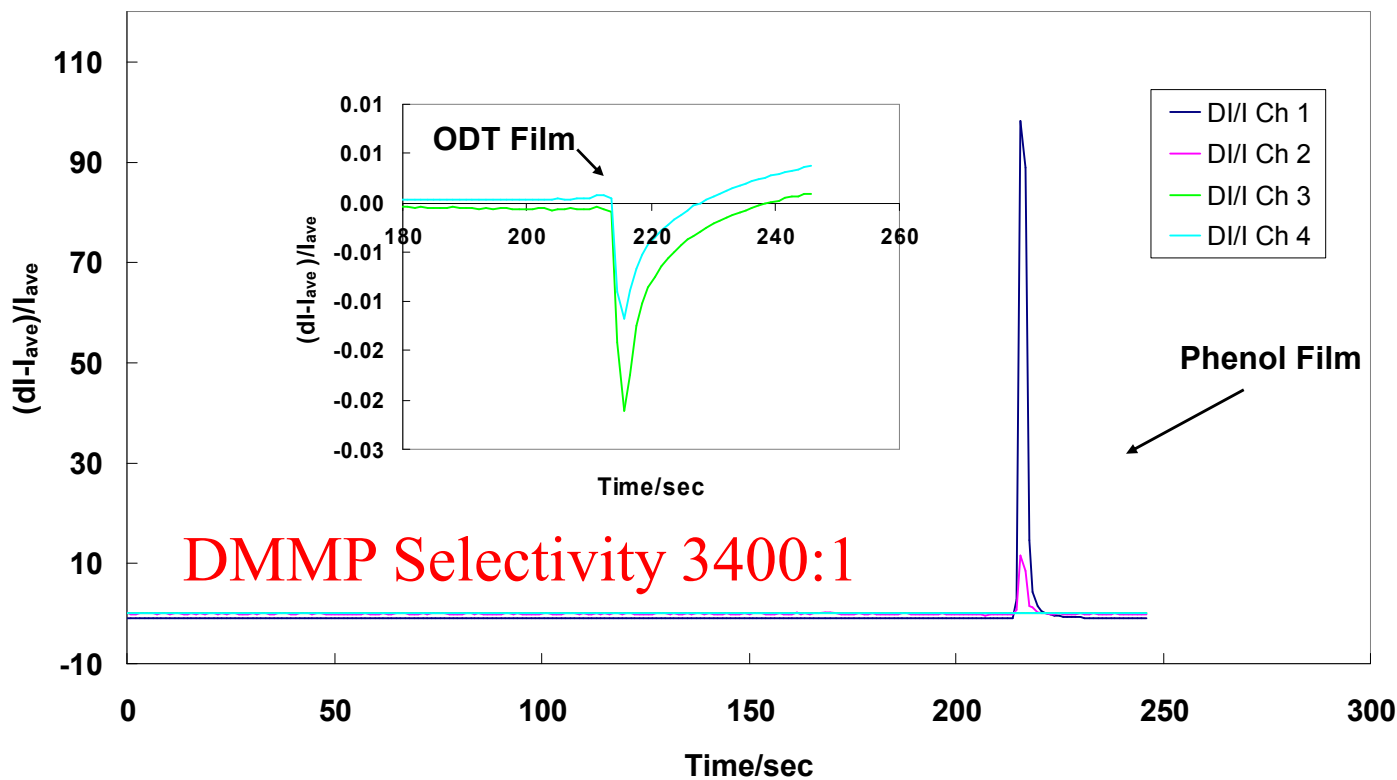


Initial Vapor sensing of DMMP using a protected phenol

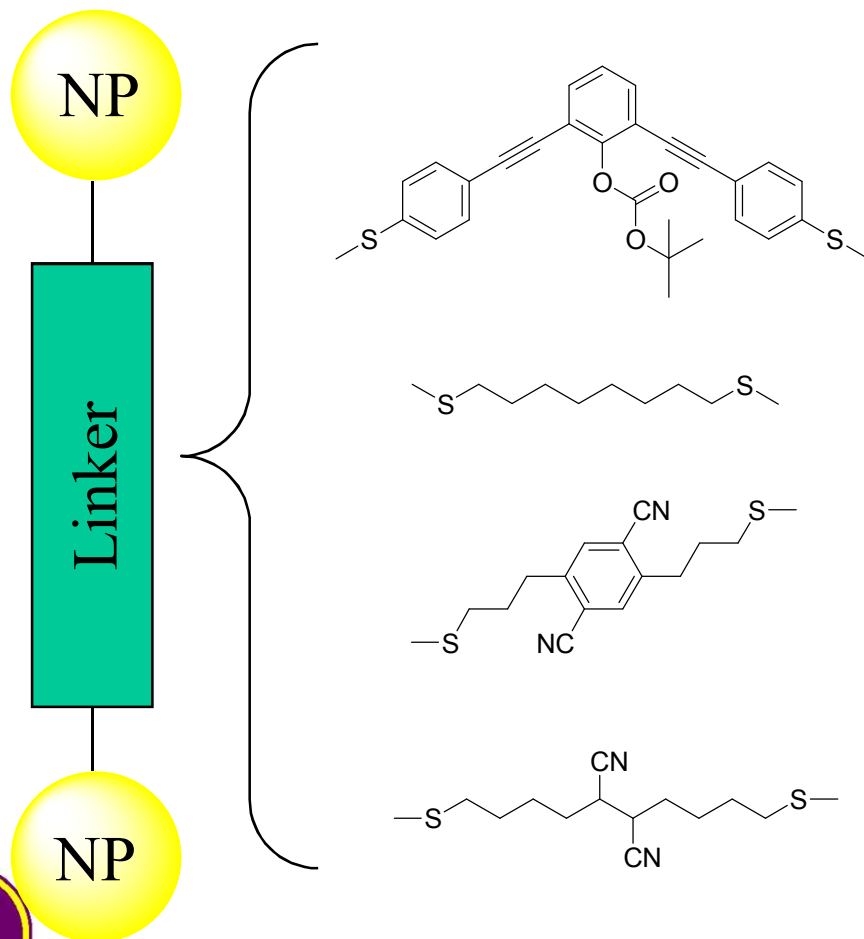
Our initial observations during exposure to DMMP show:

- Protected phenol-Au films have dramatically increased conduction (molecular electronic effect)
- Control ODT-Au films have a slight decrease in conduction (swelling)
- 10^{-4} J per detector channel per analysis!

DMMP vapor from Tenax PC using Boc Protected Phenol Molecule as Ch 1 and Ch 2 and ODT as Ch 3 and Ch 4 both with Au nanoparticles



Additional Sensor Channel Candidates

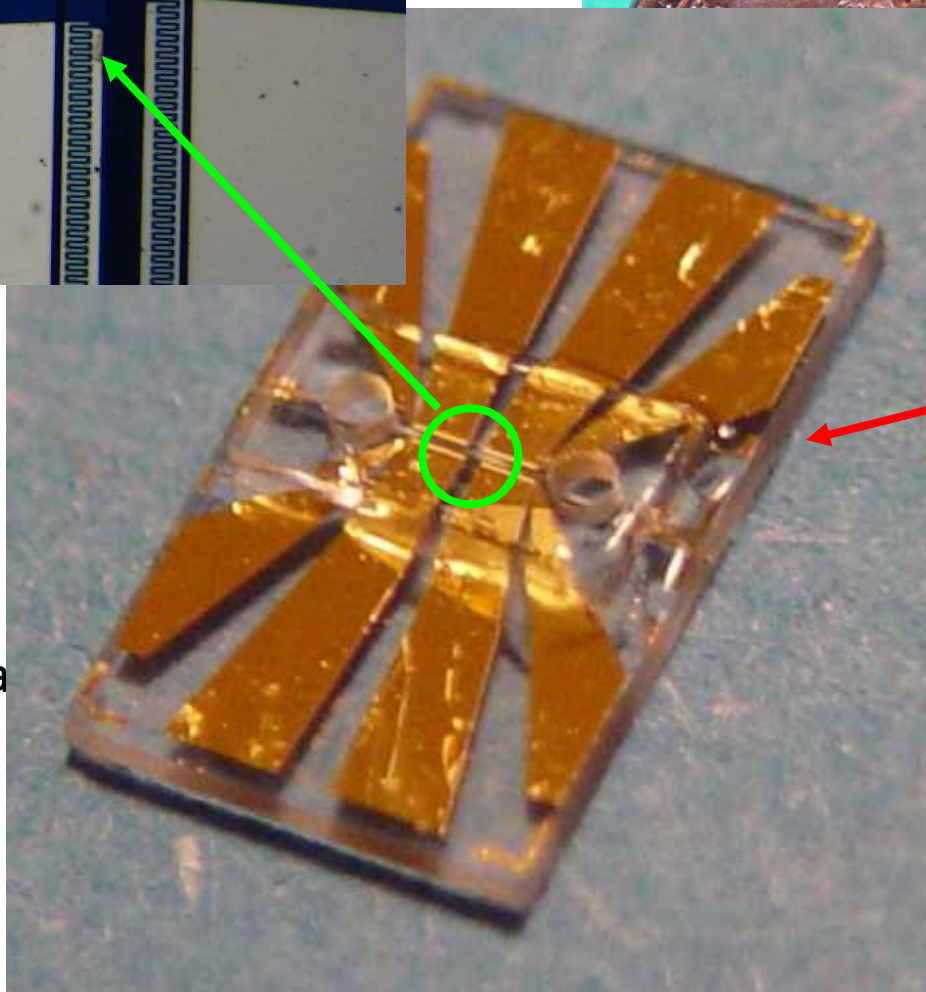
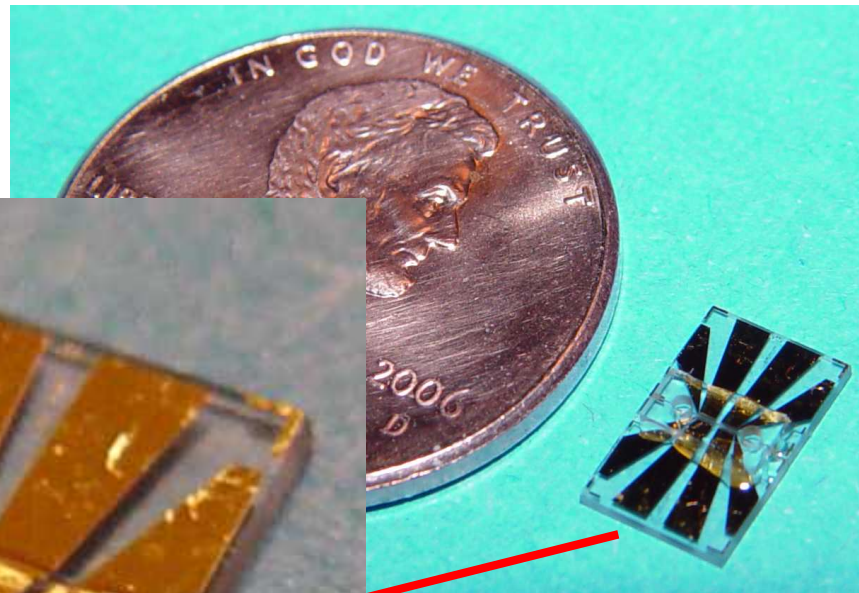
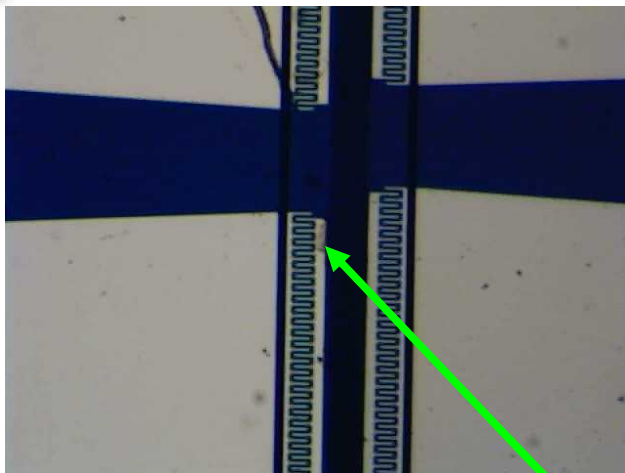


- Phosphonate-selective
- Electron hopping?

Swelling mechanism, nonpolar

- Swelling mechanism
- Vary polarity, polarizability
- Changing partition coefficients adds information to array response, increasing analytical power

Nanoparticle IDT Arrays

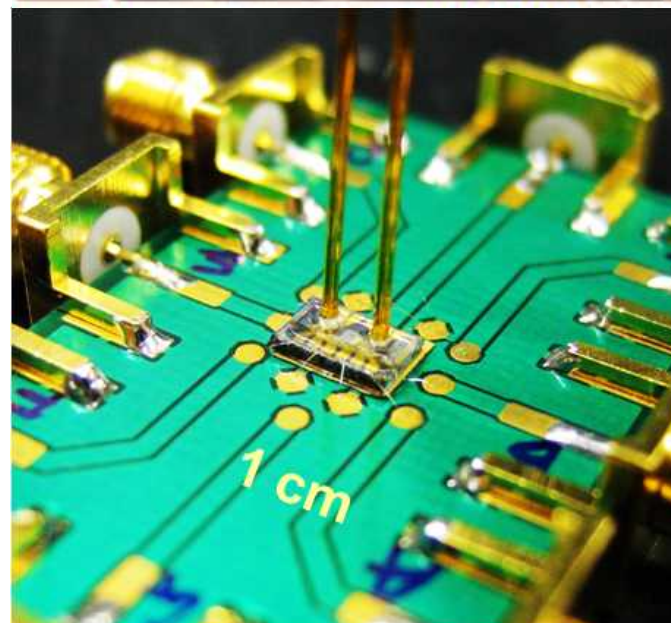
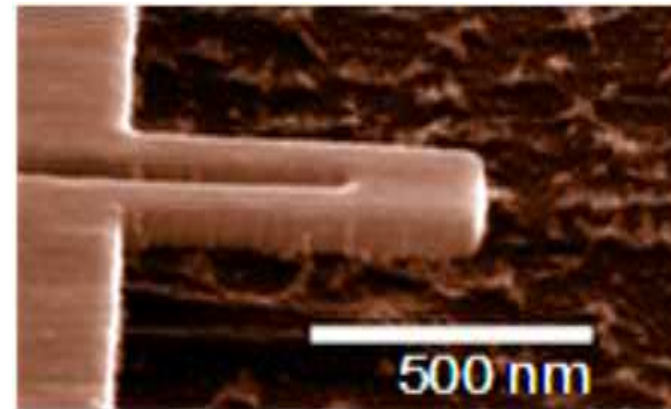


Two quartz
nanoparticle IDT
chips covered by a
flow lid

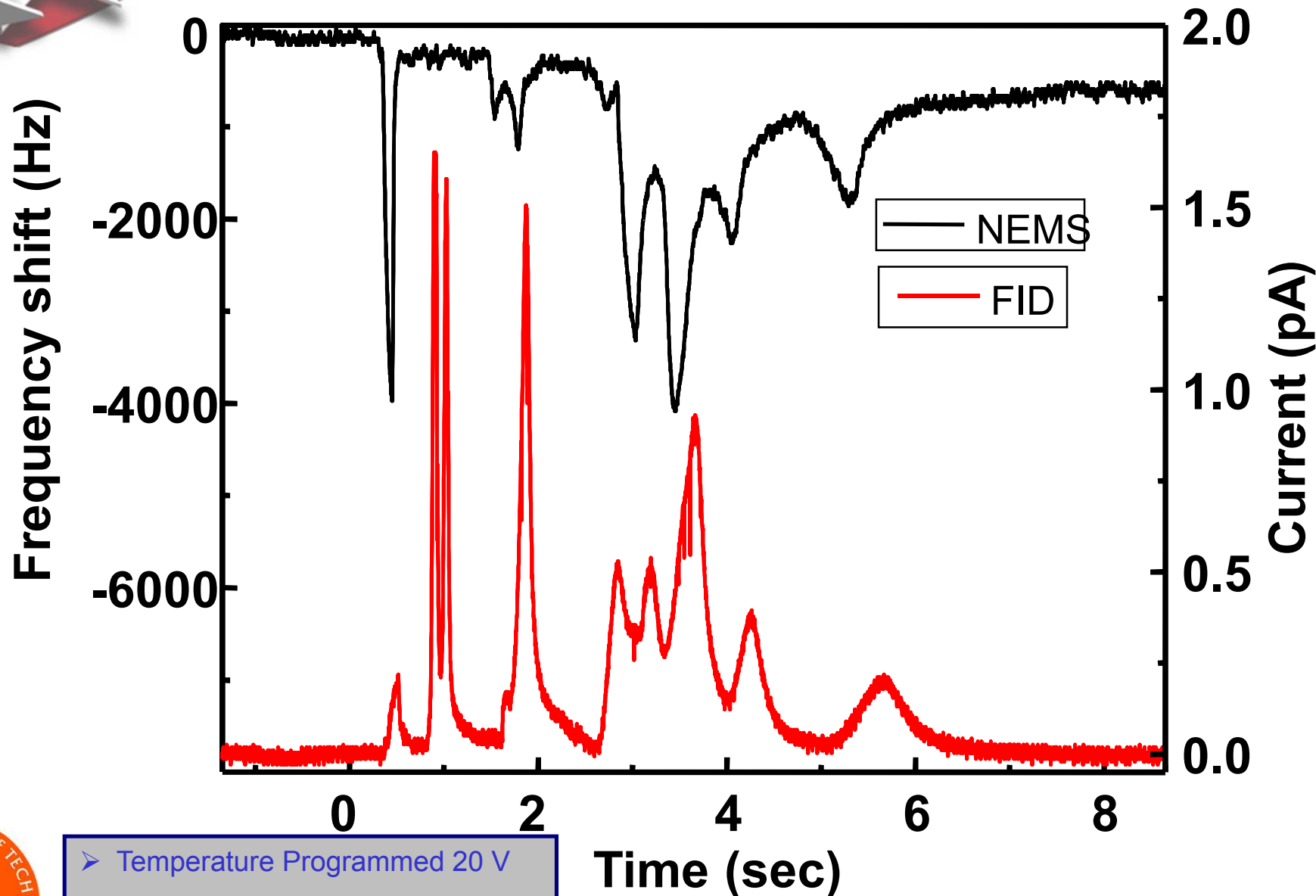
0.5 mm thick
glass with 685
micron capillary
holes

CalTech - NEMS Cantilever Resonators for GC Detection

- **100 zg** Noise floor at ambient temperature and pressure
- Low Power $< 1\mu\text{W}$
- High Frequency $> 1\text{GHz}$
- High Q values even in ambient air because of low active mass



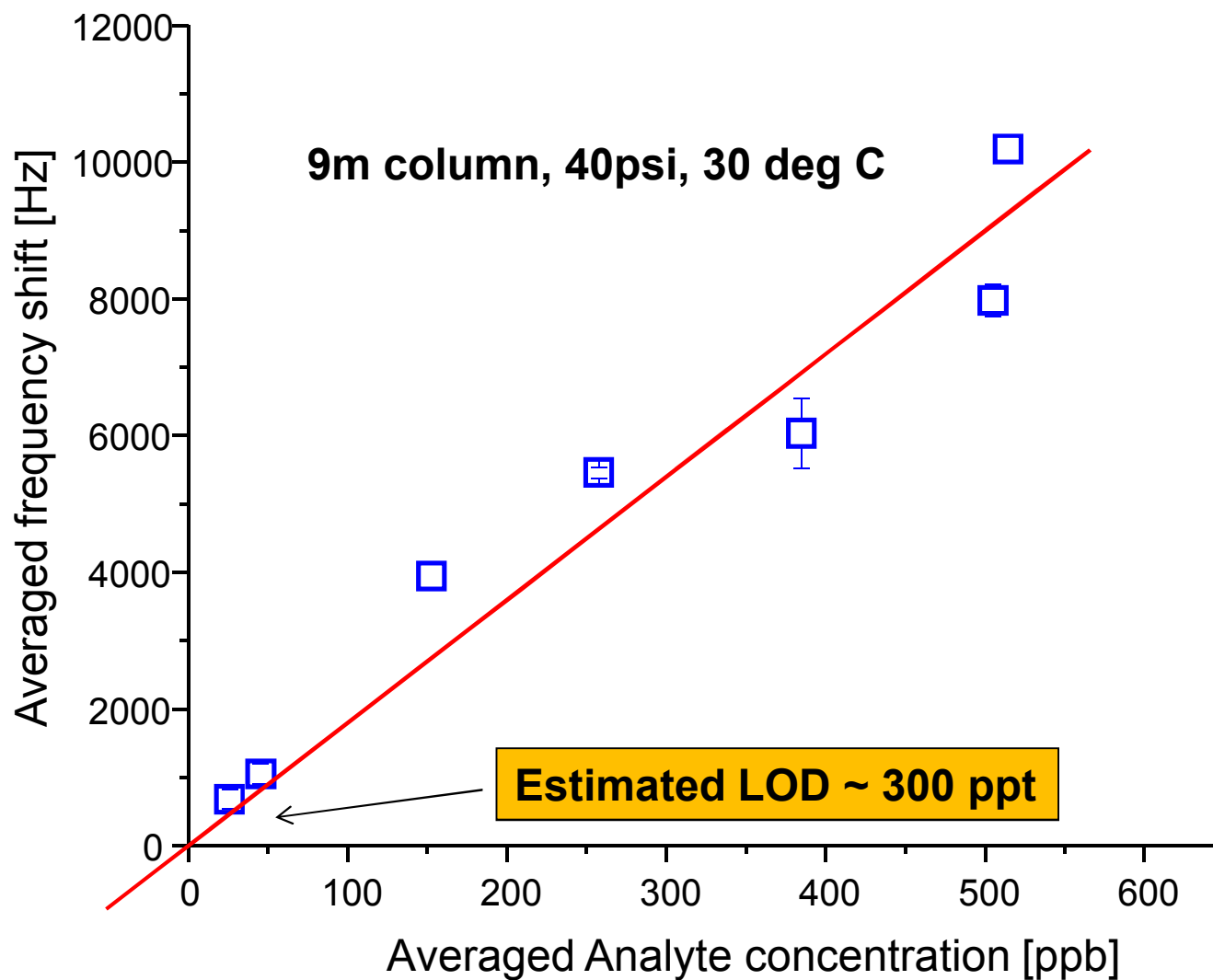
Fast GC with NEMS: 14 peaks in 6 seconds



- Temperature Programmed 20 V
- 30 PSI head pressure
- 8 simulants, 6 interferents



Detector Response

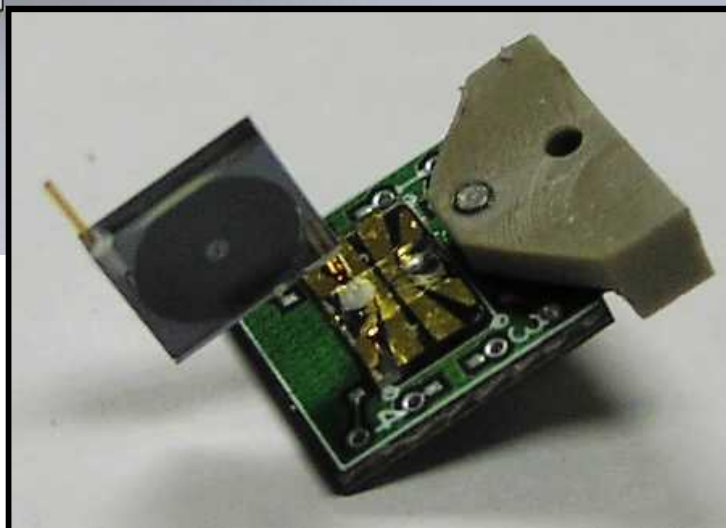
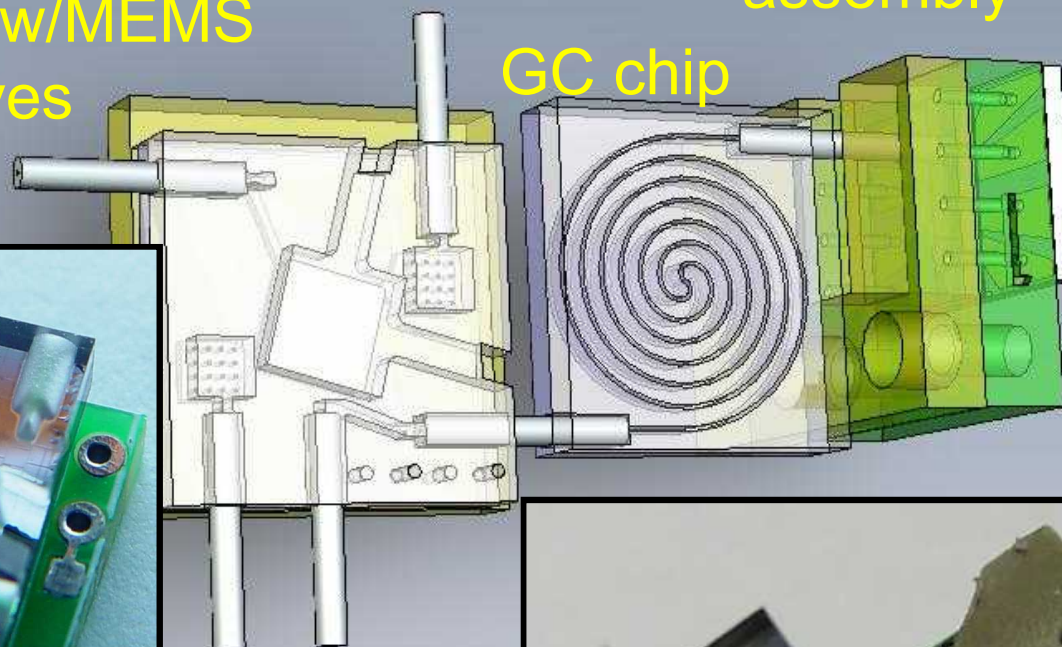
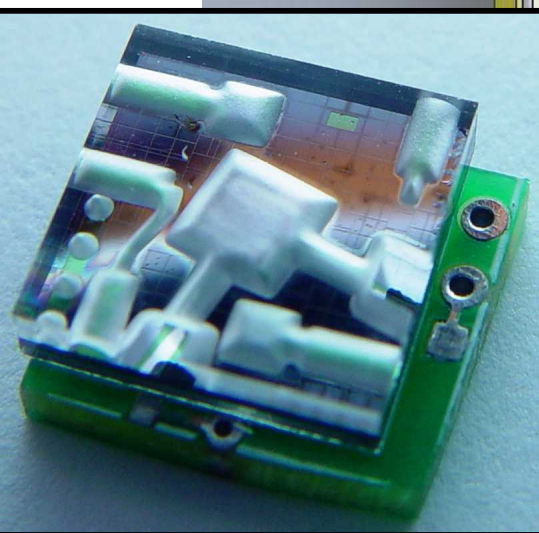


MicroFluidic Sub-Assembly

PC w/MEMS
valves

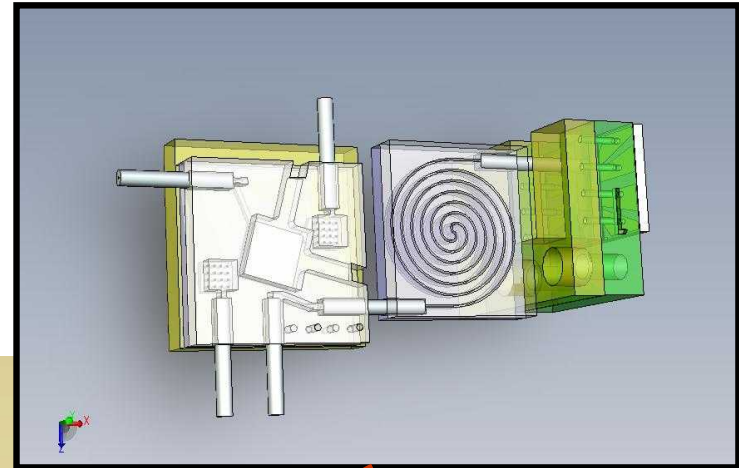
GC chip

Detector chip
assembly



Total Fluidic System Assembly

Micro Fluidic Assembly



COTS control valves

Gas manifold

PC chip

GC chip

COTS
Sampling
pump





Future Work

- Modify fabrication of column structures to increase yield and minimize “grass” at the bottom of the high aspect channel structures
- Coat and test integrated PC and valve structure
- System testing

